

Data sheet acquired from Harris Semiconductor

CD74HC257, CD74HCT257

High Speed CMOS Logic Quad 2-Input Multiplexer with Three-State Non-Inverting Outputs

November 1997

Features

- · Buffered Inputs
- Typical Propagation Delay (In to Output) = 12ns at V_{CC} = 5V, C_L = 15pF, T_A = 25°C
- Fanout (Over Temperature Range)
 - Standard Outputs................ 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)
 - CMOS Input Compatibility, $I_I \le 1\mu A$ at V_{OL} , V_{OH}

Description

The Harris CD74HC257 and CD74HCT257 are quad 2-input multiplexers which select four bits of data from two sources under the control of a common Select Input (S). The Output Enable input (\overline{OE}) is active LOW. When \overline{OE} is HIGH, all of the outputs (1Y-4Y) are in the high impedance state regardless of all other input conditions.

Moving data from two groups of registers to four common output busses is a common use of the 257. The state of the Select input determines the particular register from which the data comes. It can also be used as a function generator.

Ordering Information

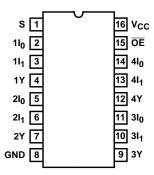
PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC257E	-55 to 125	16 Ld PDIP	E16.3
CD74HCT257E	-55 to 125	16 Ld PDIP	E16.3
CD74HC257M	-55 to 125	16 Ld SOIC	M16.15
CD74HCT257M	-55 to 125	16 Ld SOIC	M16.15

NOTES:

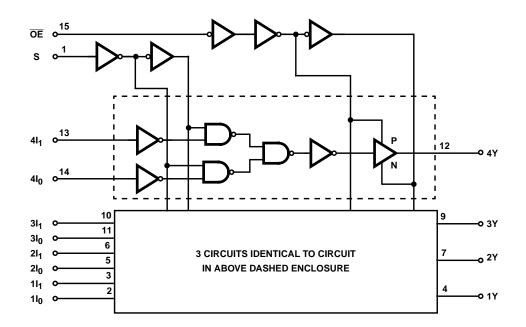
- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- Wafer or die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

Pinout

CD74HC257, CD74HC257 (PDIP, SOIC) TOP VIEW



Functional Diagram



TRUTH TABLE

OUTPUT ENABLE	SELECT INPUT	DATA I	OUTPUT		
ŌĒ	S	I ₀ I ₁		Y	
Н	Х	Х	Х	Z	
L	L	L	Х	L	
L	L	Н	Х	Н	
L	Н	Х	L	L	
L	Н	Х	Н	Н	

NOTE:

H = High Voltage Level

L = Low Voltage Level X = Don't Care

Z = High Impedance, OFF State

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Absolute Maximum Ratings

DC Supply Voltage, V $_{CC}$... -0.5V to 7V DC Input Diode Current, I $_{IK}$ For V $_{I}$ < -0.5V or V $_{I}$ > V $_{CC}$ + 0.5V ± 20 mA DC Output Diode Current, I $_{OK}$ For V $_{O}$ < -0.5V or V $_{O}$ > V $_{CC}$ + 0.5V ± 20 mA DC Drain Current, per Output, I $_{O}$ For -0.5V < V $_{O}$ < V $_{CC}$ + 0.5V ± 35 mA DC Output Source or Sink Current per Output Pin, I $_{O}$ For V $_{O}$ > -0.5V or V $_{O}$ < V $_{CC}$ + 0.5V ± 25 mA DC V $_{CC}$ or Ground Current, I $_{CC}$... ± 25 mA

Thermal Information

Thermal Resistance (Typical, Note 3) θ_{JA} (0	C/W)
PDIP Package	90
	160
Maximum Junction Temperature	150°C
Maximum Storage Temperature Range65°C to	150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

Operating Conditions

Temperature Range, T _A 55°C to 125°C
Supply Voltage Range, V _{CC}
HC Types2V to 6V
HCT Types
DC Input or Output Voltage, V _I , V _O 0V to V _{CC}
Input Rise and Fall Time
2V
4.5V 500ns (Max)
6V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

3. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

			ST ITIONS	25°C			-40°C TO 85°C		-55°C TO 125°C					
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS		
HC TYPES							-							
High Level Input	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V		
Voltage				4.5	3.15	-	-	3.15	-	3.15	-	V		
				6	4.2	-	-	4.2	-	4.2	-	V		
Low Level Input	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V		
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	V		
				6	-	-	1.8	-	1.8	-	1.8	V		
High Level Output	V _{OH}	V _{IH} or	-0.02	2	1.9	-	-	1.9	-	1.9	-	V		
Voltage CMOS Loads		V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V		
					-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output	1		-6	4.5	3.98	-	-	3.84	-	3.7	-	V		
Voltage TTL Loads			-7.8	6	5.48	-	-	5.34	-	5.2	-	V		
Low Level Output	V _{OL}	V _{IH} or	0.02	2	-	-	0.1	-	0.1	-	0.1	V		
Voltage CMOS Loads		V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V		
			0.02	6	-	-	0.1	-	0.1	-	0.1	V		
Low Level Output	·	-	-	0.26	-	0.33	-	0.4	V					
Voltage TTL Loads			7.8	6	-	-	0.26	-	0.33	-	0.4	V		
Input Leakage Current	l _l	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μА		

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DC Electrical Specifications (Continued)

	TEST CONDITIONS		25°C			-40°C T	O 85°C	-55°C TO 125°C				
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Quiescent Device Current	Icc	V _{CC} or GND	0	6	-	-	8	-	80	-	160	μА
Three-State Leakage Current	l _{OZ}	V _{IL} or V _{IH}	-	6	-	-	±0.5	-	±5	-	±10	μΑ
HCT TYPES	•		•				•				•	
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{ОН}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-6	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			6	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	II	V _{CC} to GND	0	5.5	-	-	±0.1	-	±1	-	±1	μΑ
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	5.5	-	-	8	-	80	-	160	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load (Note 4)	Δl _{CC}	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μА
Three-State Leakage Current	loz	V _{IL} or V _{IH}	-	5.5	-	-	±0.5	-	±5	-	±10	μА

NOTE:

HCT Input Loading Table

INPUT	UNIT LOADS
Data	0.95
S	3
ŌĒ	0.6

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g., 360 μA max at 25°C.

^{4.} For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

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Switching Specifications Input t_r , $t_f = 6ns$

		TEST		25	o _C	-40°C TO 85°C	-55°C TO 125°C	
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	TYP	MAX	MAX	MAX	UNITS
HC TYPES								
Propagation Delay In to Y	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	150	190	225	ns
III to 1			4.5	•	30	38	45	ns
		C _L = 15pF	5	12	-	-	-	ns
		CL = 50pF	6	-	26	33	38	ns
Propagation Delay	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	175	220	265	ns
S to Y			4.5	-	35	44	53	ns
		C _L = 15pF	5	14	-	-	-	ns
		CL = 50pF	6	-	30	37	45	ns
Propagation Delay	t _{PLZ} , t _{PHZ} ,	CL = 50pF	2	-	150	190	225	ns
OE to Y	t _{PZL} , t _{PZH}	C _L = 50pF	4.5	-	30	38	45	ns
		C _L = 15pF	5	12	-	-	-	ns
		CL = 50pF	6	-	26	33	38	ns
Output Transition Times	t _{TLH} , t _{THL}	C _L = 50pF	2	-	60	75	90	ns
			4.5	-	12	15	18	ns
			6	-	10	13	15	ns
Input Capacitance	Cl	-	-	-	10	10	10	pF
Three-State Output Capacitance	CO	-	-	-	20	20	20	pF
Power Dissipation Capacitance (Notes 5, 6)	C _{PD}	-	5	45	-	-	-	pF
HCT TYPES	_						!	
Propagation Delay	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	33	41	50	ns
In to Y		C _L = 15pF	5	13	-	-	-	ns
Propagation Delay	t _{PZL} , t _{PZH}	C _L = 50pF	4.5	-	38	48	57	ns
S to Y		C _L = 15pF	5	12	-	-	-	ns
Propagation Delay	t _{PLZ} , t _{PHZ}	C _L = 50pF	4.5	-	30	38	45	ns
OE to Y		C _L = 15pF	5	16	-	-	-	ns
Output Transition Times	t _{TLH} , t _{THL}	C _L = 50pF	4.5	-	12	15	18	ns
Input Capacitance	Cl	-	-	-	10	10	10	pF
Three-State Output Capacitance	CO	-	-	-	20	20	20	pF
Power Dissipation Capacitance (Notes 5, 6)	C _{PD}	-	5	45	-	-	-	pF

NOTES:

- 5. C_{PD} is used to determine the dynamic power consumption, per multiplexer.
 6. P_D = V_{CC}² f_i (C_{PD} + C_L) where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms

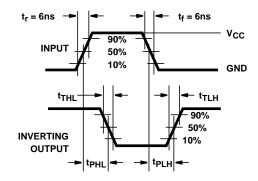


FIGURE 1. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

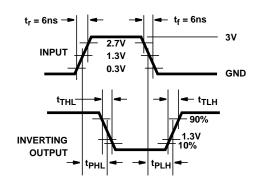


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

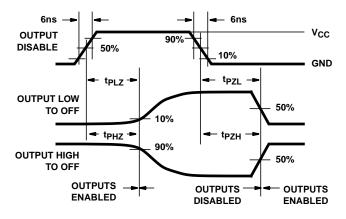


FIGURE 3. HC THREE-STATE PROPAGATION DELAY WAVEFORM

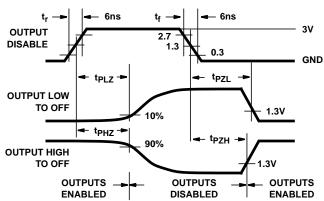
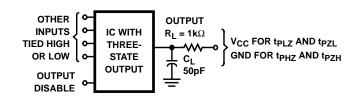


FIGURE 4. HCT THREE-STATE PROPAGATION DELAY WAVEFORM



NOTE: Open drain waveforms t_{PLZ} and t_{PZL} are the same as those for three-state shown on the left. The test circuit is Output $R_L = 1k\Omega$ to V_{CC} , $C_L = 50pF$.

FIGURE 5. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT

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